PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5490602

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	CORRECTION TO FIRST ASSIGNEE'S STREET ADDRESS, CITY, AND POSTAL CODE, AND TO SECOND ASSIGNEE'S POSTAL CODE. REEL 048813/FRAME 0432

CONVEYING PARTY DATA

Name	Execution Date
BONDTECH CO., LTD.	03/11/2019
TAIYO YUDEN CO., LTD.	03/07/2019
LAN TECHNICAL SERVICE CO., LTD.	03/11/2019
TADATOMO SUGA	03/29/2019

RECEIVING PARTY DATA

Name:	BONDTECH CO., LTD
Street Address:	77, ISHIHARANISHIMACHI, KISSHOIN, MINAMI-KU
City:	KYOTO-SHI, KYOTO
State/Country:	JAPAN
Postal Code:	601-8366
Name:	LAN TECHNICAL SERVICE CO., LTD.
Street Address:	38-2, YOYOGI 1-CHOME, SHIBUYA-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	151-0053
Name:	TADATOMO SUGA
Street Address:	6-3 HIGASHINAKANO 3-CHOME, NAKANO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	164-0003

PROPERTY NUMBERS Total: 1

Property Type	Number
Patent Number:	9601350

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 2165791700

Email: lthompson@pearne.com
Correspondent Name: PEARNE & GORDON LLP
Address Line 1: 1801 EAST 9TH STREET
Address Line 2: SUITE 1200
Address Line 4: CLEVELAND, OHIO 44114

ATTORNEY DOCKET NUMBER:	S&P-51434
NAME OF SUBMITTER:	GREGORY M. YORK
SIGNATURE:	/Gregory M. York/
DATE SIGNED:	04/24/2019

Total Attachments: 22
source=S_P-51434-Corrected-Assignment-2019-04-16#page1.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page2.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page3.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page4.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page5.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page6.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page7.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page8.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page9.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page10.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page11.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page12.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page13.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page14.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page15.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page16.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page17.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page18.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page19.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page20.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page21.tif
source=S_P-51434-Corrected-Assignment-2019-04-16#page22.tif

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5459870

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
BONDTECH CO., LTD.	03/11/2019
TAIYO YUDEN CO., LTD.	03/07/2019
LAN TECHNICAL SERVICE CO., LTD.	03/11/2019
TADATOMO SUGA	03/29/2019

RECEIVING PARTY DATA

Name:	BONDTECH CO., LTD.
Street Address:	~~16-20, UENO 6-CHOME, TAITO-KU~~ 77, ISHIHARANISHIMACHI, KISSHOIN, MINAMI-KU
City:	~~TOKYO~~ KYOTO-SHI, KYOTO
State/Country:	JAPAN
Postal Code:	~~110-0005~~ 601-8366
Name:	LAN TECHNICAL SERVICE CO., LTD.
Street Address:	38-2, YOYOGI 1-CHOME, SHIBUYA-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	~~164-0003~~ 151-0053
Name:	TADATOMO SUGA
Street Address:	6-3 HIGASHINAKANO 3-CHOME, NAKANO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	164-0003

PROPERTY NUMBERS Total: 1

Property Type	Number
Patent Number:	9601350

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 2165791700
Email: lthompson@pearne.com

Correspondent Name:	PEARNE & GORDON LLP
Address Line 1:	1801 EAST 9TH STREET
Address Line 2:	SUITE 1200
Address Line 4:	CLEVELAND, OHIO 44114

ATTORNEY DOCKET NUMBER:	S&P-54134
NAME OF SUBMITTER:	GREGORY M. YORK
SIGNATURE:	/Gregory M. York/
DATE SIGNED:	04/05/2019

Total Attachments: 20
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page1.tif
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page2.tif
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page3.tif
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page4.tif
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page5.tif
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page6.tif
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page7.tif
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page8.tif
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page9.tif
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page10.tif
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page11.tif
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page12.tif
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page13.tif
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page14.tif
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page15.tif
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page16.tif
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page17.tif
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page18.tif
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page19.tif
source=S&P-51434-Executed-Assignment--4-Owners-to-3-Owners#page20.tif

ASSIGNMENT

WHEREAS, **BONDTECH CO., LTD.**, a corporation of Japan, having a place of business at 77, Ishiharanishimachi, Kisshoin, Minami-ku, Kyoto-shi, Kyoto 601-8366 JAPAN, and **TAIYO YUDEN CO., LTD.**, a corporation of Japan, having a place of business at 16-20, Ueno 6-chome, Taito-ku, Tokyo 110-0005 JAPAN, and **LAN TECHNICAL SERVICE CO., LTD.**, a corporation of Japan, having a place of business at 38-2, Yoyogi 1-chome, Shibuya-ku, Tokyo 151-0053 JAPAN, and **Tadatomo SUGA**, an individual residing at 6-3, Higashinakano 3-chome, Nakano-ku, Tokyo 164-0003 JAPAN, hereinafter referred to as "ASSIGNORS", are joint owners of the entire right, title, and interest to, in, and under the following patent and corresponding patent application:

U.S. PATENT NO. 9,601,350

BONDING-SUBSTRATE FABRICATION METHOD, BONDING SUBSTRATE, SUBSTRATE BONDING METHOD, BONDING-SUBSTRATE FABRICATION APPARATUS, AND SUBSTRATE ASSEMBLY

which issued March 21, 2017
from U.S. Application No. 13/982,697,
having a 371(c) date of October 17, 2013, and
a PCT filing date of January 30, 2012

WHEREAS, the same **BONDTECH CO., LTD.**, and the same **LAN TECHNICAL SERVICE CO., LTD.**, and the same **Tadatomo SUGA**, hereinafter referred to as "ASSIGNEES", are desirous of acquiring all right, title, and interest in, to, and under said patent and corresponding patent application;

NOW, THEREFORE, be it known that, for valuable consideration, the receipt and sufficiency of which are hereby acknowledged, ASSIGNORS do hereby sell, assign, and transfer to ASSIGNEES all right, title, and interest, in the United States, in, to, and for (1) certain inventions or improvements described in said patent and corresponding patent application, (2) said patent and corresponding patent application, (3) all Letters Patent of the United States which may or shall be granted on said inventions, on said improvements, or on said patent and corresponding patent application, (4) all provisional, divisional, continuation, reissue, or other applications based thereon, and (5) all rights of priority, including the right to claim priority to said patent and corresponding patent application, together with all rights to sue for past, present, or future infringement thereof, including the right to collect damages for any past infringement thereto.

ASSIGNORS agree with ASSIGNEES, but at ASSIGNEES' expense, hereafter to execute all applications, amended specifications, deeds or other instruments, and to do all acts necessary or proper to secure the grant of Letters Patent in the United States to said ASSIGNEES, with specifications and claims in such form as shall be approved by the counsel of said ASSIGNEES, and to vest and confirm in said ASSIGNEES, their successors and assigns, the legal title to all such patents.

ASSIGNORS hereby authorize and request the Director of the United States Patent and Trademark Office to issue such Letters Patent as shall be granted upon said application(s) based thereon to said ASSIGNEES, their successors and assigns.

ASSIGNORS do hereby authorize ASSIGNEES' attorney to correct any typographical errors on this form, if necessary, and to complete this form by the addition of patent number(s), patent issue date(s), patent title(s), application number(s), application filing date(s), application title(s), attorney docket number(s), or other further identification, if necessary.

IN WITNESS WHEREOF, this Assignment has been executed below by the ASSIGNORS:

Assignor: BONDTECH CO., LTD.

By: Akira Yamauchi

Signature: ______________________

Title: President

Date: March / 11 / 2019

Witness: ______________________

Witness: Naho Shinkai

Assignor: TAIYO YUDEN CO., LTD.

By: Shigetoshi Akino

Signature: ______________________

Title: General Manager

Date: ______________________

Witness: ______________________

Witness: ______________________

Assignor: LAN TECHNICAL SERVICE CO., LTD.

By: Yoshiie Matsumoto

Signature: ______________________________

Title: President

Date: ______________________________

Witness: ______________________________

Witness: ______________________________

Assignor: Tadatomo SUGA

Signature: ______________________________

Date: ______________________________

Witness: ______________________________

Witness: ______________________________

[Acceptance of Assignment follows]

ACCEPTANCE OF ASSIGNMENT

BONDTECH CO., LTD., LAN TECHNICAL SERVICE CO., LTD., and Tadatomo SUGA, do hereby declare that they have accepted from BONDTECH CO., LTD., TAIYO YUDEN CO., LTD., LAN TECHNICAL SERVICE CO., LTD., and Tadatomo SUGA, the Assignment of all right, title, and interest, in the United States, in, to and under said improvements and inventions and all patents, patent applications, and patent rights thereof, therefor, and therein as described above.

Assignee: BONDTECH CO., LTD.

By: Akira Yamauchi

Signature: ______

Title: President

Date: March/11/ 2019

Witness: Kumiko Ikemoto.

Witness: Naho Shinkai

Assignee: LAN TECHNICAL SERVICE CO., LTD.

By: Yoshiie Matsumoto

Signature: ______

Title: President

Date: ______

Witness: ______

Witness: ______

Assignee: Tadatomo SUGA

Signature: ______________________________

Date: ______________________________

Witness: ______________________________

Witness: ______________________________

ASSIGNMENT

WHEREAS, **BONDTECH CO., LTD.**, a corporation of Japan, having a place of business at 77, Ishiharanishimachi, Kisshoin, Minami-ku, Kyoto-shi, Kyoto 601-8366 JAPAN, and **TAIYO YUDEN CO., LTD**., a corporation of Japan, having a place of business at 16-20, Ueno 6-chome, Taito-ku, Tokyo 110-0005 JAPAN, and **LAN TECHNICAL SERVICE CO., LTD.**, a corporation of Japan, having a place of business at 38-2, Yoyogi 1-chome, Shibuya-ku, Tokyo 151-0053 JAPAN, and **Tadatomo SUGA**, an individual residing at 6-3, Higashinakano 3-chome, Nakano-ku, Tokyo 164-0003 JAPAN, hereinafter referred to as "ASSIGNORS", are joint owners of the entire right, title, and interest to, in, and under the following patent and corresponding patent application:

U.S. PATENT NO. 9,601,350

BONDING-SUBSTRATE FABRICATION METHOD, BONDING SUBSTRATE, SUBSTRATE BONDING METHOD, BONDING-SUBSTRATE FABRICATION APPARATUS, AND SUBSTRATE ASSEMBLY

which issued March 21, 2017
from U.S. Application No. 13/982,697,
having a 371(c) date of October 17, 2013, and
a PCT filing date of January 30, 2012

WHEREAS, the same **BONDTECH CO., LTD.**, and the same **LAN TECHNICAL SERVICE CO., LTD.**, and the same **Tadatomo SUGA**, hereinafter referred to as "ASSIGNEES", are desirous of acquiring all right, title, and interest in, to, and under said patent and corresponding patent application;

NOW, THEREFORE, be it known that, for valuable consideration, the receipt and sufficiency of which are hereby acknowledged, ASSIGNORS do hereby sell, assign, and transfer to ASSIGNEES all right, title, and interest, in the United States, in, to, and for (1) certain inventions or improvements described in said patent and corresponding patent application, (2) said patent and corresponding patent application, (3) all Letters Patent of the United States which may or shall be granted on said inventions, on said improvements, or on said patent and corresponding patent application, (4) all provisional, divisional, continuation, reissue, or other applications based thereon, and (5) all rights of priority, including the right to claim priority to said patent and corresponding patent application, together with all rights to sue for past, present, or future infringement thereof, including the right to collect damages for any past infringement thereto.

ASSIGNORS agree with ASSIGNEES, but at ASSIGNEES' expense, hereafter to execute all applications, amended specifications, deeds or other instruments, and to do all acts necessary or proper to secure the grant of Letters Patent in the United States to said ASSIGNEES, with specifications and claims in such form as shall be approved by the counsel of said ASSIGNEES, and to vest and confirm in said ASSIGNEES, their successors and assigns, the legal title to all such patents.

ASSIGNORS hereby authorize and request the Director of the United States Patent and Trademark Office to issue such Letters Patent as shall be granted upon said application(s) based thereon to said ASSIGNEES, their successors and assigns.

ASSIGNORS do hereby authorize ASSIGNEES' attorney to correct any typographical errors on this form, if necessary, and to complete this form by the addition of patent number(s), patent issue date(s), patent title(s), application number(s), application filing date(s), application title(s), attorney docket number(s), or other further identification, if necessary.

IN WITNESS WHEREOF, this Assignment has been executed below by the ASSIGNORS:

Assignor: BONDTECH CO., LTD.

By: Akira Yamauchi

Signature: ____________________

Title: President

Date: ____________________

Witness: ____________________

Witness: ____________________

Assignor: TAIYO YUDEN CO., LTD.

By: Shigetoshi Akino

Signature:

Title: General Manager

Date: March 7, 2019

Witness: Toshiyuki Kagawa

Witness:

Assignor: LAN TECHNICAL SERVICE CO., LTD.

By: Yoshiie Matsumoto

Signature: ______________________________

Title: President

Date: ______________________________

Witness: ______________________________

Witness: ______________________________

Assignor: Tadatomo SUGA

Signature: ______________________________

Date: ______________________________

Witness: ______________________________

Witness: ______________________________

[Acceptance of Assignment follows]

ACCEPTANCE OF ASSIGNMENT

BONDTECH CO., LTD., LAN TECHNICAL SERVICE CO., LTD., and Tadatomo SUGA, do hereby declare that they have accepted from BONDTECH CO., LTD., TAIYO YUDEN CO., LTD., LAN TECHNICAL SERVICE CO., LTD., and Tadatomo SUGA, the Assignment of all right, title, and interest, in the United States, in, to and under said improvements and inventions and all patents, patent applications, and patent rights thereof, therefor, and therein as described above.

Assignee: BONDTECH CO., LTD.

By: Akira Yamauchi

Signature: ______________________________

Title: President

Date: ______________________________

Witness: ______________________________

Witness: ______________________________

Assignee: LAN TECHNICAL SERVICE CO., LTD.

By: Yoshiie Matsumoto

Signature: ______________________________

Title: President

Date: ______________________________

Witness: ______________________________

Witness: ______________________________

Assignee: Tadatomo SUGA

Signature: ______________________

Date: ______________________

Witness: ______________________

Witness: ______________________

ASSIGNMENT

WHEREAS, **BONDTECH CO., LTD.**, a corporation of Japan, having a place of business at 77, Ishiharanishimachi, Kisshoin, Minami-ku, Kyoto-shi, Kyoto 601-8366 JAPAN, and **TAIYO YUDEN CO., LTD.**, a corporation of Japan, having a place of business at 16-20, Ueno 6-chome, Taito-ku, Tokyo 110-0005 JAPAN, and **LAN TECHNICAL SERVICE CO., LTD.**, a corporation of Japan, having a place of business at 38-2, Yoyogi 1-chome, Shibuya-ku, Tokyo 151-0053 JAPAN, and **Tadatomo SUGA**, an individual residing at 6-3, Higashinakano 3-chome, Nakano-ku, Tokyo 164-0003 JAPAN, hereinafter referred to as "ASSIGNORS", are joint owners of the entire right, title, and interest to, in, and under the following patent and corresponding patent application:

U.S. PATENT NO. 9,601,350

BONDING-SUBSTRATE FABRICATION METHOD, BONDING SUBSTRATE, SUBSTRATE BONDING METHOD, BONDING-SUBSTRATE FABRICATION APPARATUS, AND SUBSTRATE ASSEMBLY

which issued March 21, 2017
from U.S. Application No. 13/982,697,
having a 371(c) date of October 17, 2013, and
a PCT filing date of January 30, 2012

WHEREAS, the same **BONDTECH CO., LTD.**, and the same **LAN TECHNICAL SERVICE CO., LTD.**, and the same **Tadatomo SUGA**, hereinafter referred to as "ASSIGNEES", are desirous of acquiring all right, title, and interest in, to, and under said patent and corresponding patent application;

NOW, THEREFORE, be it known that, for valuable consideration, the receipt and sufficiency of which are hereby acknowledged, ASSIGNORS do hereby sell, assign, and transfer to ASSIGNEES all right, title, and interest, in the United States, in, to, and for (1) certain inventions or improvements described in said patent and corresponding patent application, (2) said patent and corresponding patent application, (3) all Letters Patent of the United States which may or shall be granted on said inventions, on said improvements, or on said patent and corresponding patent application, (4) all provisional, divisional, continuation, reissue, or other applications based thereon, and (5) all rights of priority, including the right to claim priority to said patent and corresponding patent application, together with all rights to sue for past, present, or future infringement thereof, including the right to collect damages for any past infringement thereto.

ASSIGNORS agree with ASSIGNEES, but at ASSIGNEES' expense, hereafter to execute all applications, amended specifications, deeds or other instruments, and to do all acts necessary or proper to secure the grant of Letters Patent in the United States to said ASSIGNEES, with specifications and claims in such form as shall be approved by the counsel of said ASSIGNEES, and to vest and confirm in said ASSIGNEES, their successors and assigns, the legal title to all such patents.

ASSIGNORS hereby authorize and request the Director of the United States Patent and Trademark Office to issue such Letters Patent as shall be granted upon said application(s) based thereon to said ASSIGNEES, their successors and assigns.

ASSIGNORS do hereby authorize ASSIGNEES' attorney to correct any typographical errors on this form, if necessary, and to complete this form by the addition of patent number(s), patent issue date(s), patent title(s), application number(s), application filing date(s), application title(s), attorney docket number(s), or other further identification, if necessary.

IN WITNESS WHEREOF, this Assignment has been executed below by the ASSIGNORS:

Assignor: BONDTECH CO., LTD.

By: Akira Yamauchi

Signature: ______________________

Title: President

Date: ______________________

Witness: ______________________

Witness: ______________________

Assignor: TAIYO YUDEN CO., LTD.

By: Shigetoshi Akino

Signature: ______________________

Title: General Manager

Date: ______________________

Witness: ______________________

Witness: ______________________

Assignor: LAN TECHNICAL SERVICE CO., LTD.

By: Yoshiie Matsumoto

Signature:

Title: President

Date: 11/03/19

Witness:

Witness:

Assignor: Tadatomo SUGA

Signature:

Date:

Witness:

Witness:

[Acceptance of Assignment follows]

ACCEPTANCE OF ASSIGNMENT

BONDTECH CO., LTD., LAN TECHNICAL SERVICE CO., LTD., and Tadatomo SUGA, do hereby declare that they have accepted from BONDTECH CO., LTD., TAIYO YUDEN CO., LTD., LAN TECHNICAL SERVICE CO., LTD., and Tadatomo SUGA, the Assignment of all right, title, and interest, in the United States, in, to and under said improvements and inventions and all patents, patent applications, and patent rights thereof, therefor, and therein as described above.

Assignee: BONDTECH CO., LTD.

By: Akira Yamauchi

Signature: __________

Title: President

Date: __________

Witness: __________

Witness: __________

Assignee: LAN TECHNICAL SERVICE CO., LTD.

By: Yoshiie Matsumoto

Signature: __________

Title: President

Date: 11/03/19

Witness: __________

Witness: __________

Assignee: Tadatomo SUGA

Signature: ______________________________

Date: ______________________________

Witness: ______________________________

Witness: ______________________________

ASSIGNMENT

WHEREAS, **BONDTECH CO., LTD.**, a corporation of Japan, having a place of business at 77, Ishiharanishimachi, Kisshoin, Minami-ku, Kyoto-shi, Kyoto 601-8366 JAPAN, and **TAIYO YUDEN CO., LTD.**, a corporation of Japan, having a place of business at 16-20, Ueno 6-chome, Taito-ku, Tokyo 110-0005 JAPAN, and **LAN TECHNICAL SERVICE CO., LTD.**, a corporation of Japan, having a place of business at 38-2, Yoyogi 1-chome, Shibuya-ku, Tokyo 151-0053 JAPAN, and **Tadatomo SUGA**, an individual residing at 6-3, Higashinakano 3-chome, Nakano-ku, Tokyo 164-0003 JAPAN, hereinafter referred to as "ASSIGNORS", are joint owners of the entire right, title, and interest to, in, and under the following patent and corresponding patent application:

U.S. PATENT NO. 9,601,350

BONDING-SUBSTRATE FABRICATION METHOD, BONDING SUBSTRATE, SUBSTRATE BONDING METHOD, BONDING-SUBSTRATE FABRICATION APPARATUS, AND SUBSTRATE ASSEMBLY

which issued March 21, 2017
from U.S. Application No. 13/982,697,
having a 371(c) date of October 17, 2013, and
a PCT filing date of January 30, 2012

WHEREAS, the same **BONDTECH CO., LTD.**, and the same **LAN TECHNICAL SERVICE CO., LTD.**, and the same **Tadatomo SUGA**, hereinafter referred to as "ASSIGNEES", are desirous of acquiring all right, title, and interest in, to, and under said patent and corresponding patent application;

NOW, THEREFORE, be it known that, for valuable consideration, the receipt and sufficiency of which are hereby acknowledged, ASSIGNORS do hereby sell, assign, and transfer to ASSIGNEES all right, title, and interest, in the United States, in, to, and for (1) certain inventions or improvements described in said patent and corresponding patent application, (2) said patent and corresponding patent application, (3) all Letters Patent of the United States which may or shall be granted on said inventions, on said improvements, or on said patent and corresponding patent application, (4) all provisional, divisional, continuation, reissue, or other applications based thereon, and (5) all rights of priority, including the right to claim priority to said patent and corresponding patent application, together with all rights to sue for past, present, or future infringement thereof, including the right to collect damages for any past infringement thereto.

ASSIGNORS agree with ASSIGNEES, but at ASSIGNEES' expense, hereafter to execute all applications, amended specifications, deeds or other instruments, and to do all acts necessary or proper to secure the grant of Letters Patent in the United States to said ASSIGNEES, with specifications and claims in such form as shall be approved by the counsel of said ASSIGNEES, and to vest and confirm in said ASSIGNEES, their successors and assigns, the legal title to all such patents.

ASSIGNORS hereby authorize and request the Director of the United States Patent and Trademark Office to issue such Letters Patent as shall be granted upon said application(s) based thereon to said ASSIGNEES, their successors and assigns.

ASSIGNORS do hereby authorize ASSIGNEES' attorney to correct any typographical errors on this form, if necessary, and to complete this form by the addition of patent number(s), patent issue date(s), patent title(s), application number(s), application filing date(s), application title(s), attorney docket number(s), or other further identification, if necessary.

IN WITNESS WHEREOF, this Assignment has been executed below by the ASSIGNORS:

Assignor: BONDTECH CO., LTD.

By: Akira Yamauchi

Signature: ________________________________

Title: President

Date: ________________________________

Witness: ________________________________

Witness: ________________________________

Assignor: TAIYO YUDEN CO., LTD.

By: Shigetoshi Akino

Signature: ________________________________

Title: General Manager

Date: ________________________________

Witness: ________________________________

Witness: ________________________________

Assignor: LAN TECHNICAL SERVICE CO., LTD.

By: Yoshiie Matsumoto

Signature: ____________________

Title: President

Date: ____________________

Witness: ____________________

Witness: ____________________

Assignor: Tadatomo SUGA

Signature:

Date: March 29. 2019

Witness: Natsuko Kamamota

Witness: ____________________

[Acceptance of Assignment follows]

ACCEPTANCE OF ASSIGNMENT

BONDTECH CO., LTD., LAN TECHNICAL SERVICE CO., LTD., and Tadatomo SUGA, do hereby declare that they have accepted from BONDTECH CO., LTD., TAIYO YUDEN CO., LTD., LAN TECHNICAL SERVICE CO., LTD., and Tadatomo SUGA, the Assignment of all right, title, and interest, in the United States, in, to and under said improvements and inventions and all patents, patent applications, and patent rights thereof, therefor, and therein as described above.

Assignee: BONDTECH CO., LTD.

By: Akira Yamauchi

Signature: ______________________________

Title: President

Date: ______________________________

Witness: ______________________________

Witness: ______________________________

Assignee: LAN TECHNICAL SERVICE CO., LTD.

By: Yoshiie Matsumoto

Signature: ______________________________

Title: President

Date: ______________________________

Witness: ______________________________

Witness: ______________________________

Assignee: Tadatomo SUGA

Signature:

Date: March 29. 2019

Witness: Natsuko Kawamata

Witness: